

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/17/2022

Details for "REG104GA-3.3/2K5"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
REG104GA-3.3/2K5	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DCQ   6	6.5x3.5x1.5	130.3

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.000001	0.000407	4	0.000001	0
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000407	4	0.000001	0
Precious Metals	Gold	7440-57-5	0.245739	99.998779	999988	0.188648	1886
Precious Metals	Silver	7440-22-4	0.000001	0.000407	4	0.000001	0
Sub-Total			0.245742	100	1000000	0.188651	1887
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.521226	88.000041	880000	0.400134	4001
Thermoplastics	Epoxy	85954-11-6	0.071076	11.999959	120000	0.054563	546
Sub-Total			0.592302	100	1000000	0.454697	4547
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	67.87386	97.38	973800	52.105283	521053
Copper and Its Alloys	Iron	7439-89-6	1.65886	2.38	23800	1.273471	12735
Copper and Its Alloys	Phosphorus	7723-14-0	0.058548	0.084	840	0.044946	449
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.02091	0.03	300	0.016052	161
Zinc and Its Alloys	Zinc	7440-66-6	0.087822	0.126	1260	0.067419	674
Sub-Total			69.7	100	1000000	53.50717	535072
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	1.265096	95.12	951200	0.971187	9712
Precious Metals	Gold	7440-57-5	0.010374	0.78	7800	0.007964	80
Precious Metals	Palladium	7440-05-3	0.054533	4.1	41000	0.041861	419
Sub-Total			1.33	100	1000000	1.021012	10210
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	47.898309	85	850000	36.770488	367705
Other Plastics and Rubber	Carbon Black	1333-86-4	0.169053	0.3	3000	0.129778	1298
Thermoplastics	Epoxy	85954-11-6	8.28359	14.7	147000	6.359131	63591
Sub-Total			56.350952	100	1000000	43.259397	432594
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.043919	100	1000000	1.569072	15691
Sub-Total			2.043919	100	1000000	1.569072	15691
<b>Total</b>			130.262915			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."  
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
 Created on: 05/17/2022

**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.